



Material Content Data Sheet



Sales Product Name		BGA 777N7 E6327		Issued		23. January 2018		
MA#		MA001163604						
Package		PG-TSNP-7-1		Weight*		3.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.162	4.19	4.19	41889	41889
leadframe	non noble metal	zinc	7440-66-6	0.004	0.11		1113	
	non noble metal	tin	7440-31-5	0.005	0.14		1392	
	non noble metal	chromium	7440-47-3	0.006	0.17		1670	
wire	non noble metal	copper	7440-50-8	2.136	55.25	55.67	552500	556675
	noble metal	gold	7440-57-5	0.038	0.97	0.97	9736	9736
encapsulation	organic material	carbon black	1333-86-4	0.006	0.16		1568	
	plastics	epoxy resin	-	0.176	4.55		45460	
	inorganic material	silicondioxide	60676-86-0	1.030	26.65	31.36	266489	313517
leadfinish	non noble metal	tin	7440-31-5	0.111	2.88	2.88	28836	28836
plating	noble metal	silver	7440-22-4	0.104	2.68	2.68	26841	26841
glue	plastics	epoxy resin	-	0.017	0.45		4501	
	noble metal	silver	7440-22-4	0.070	1.80	2.25	18005	22506
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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